

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

IN RE APPLICATION OF: Hiroshi SHIHO et al.

SERIAL NUMBER: 10/529,742

FILED: March 29, 2005

FOR: POLISHING PAD FOR SEMICONDUCTOR WAFER, POLISHING  
MULTILAYERED BODY FOR SEMICONDUCTOR WAFER HAVING SAME, AND  
METHOD FOR POLISHING SEMICONDUCTOR WAFER

**RESPONSE TO NOTICE OF MISSING REQUIREMENTS UNDER 35 U.S.C. 371**

COMMISSIONER FOR PATENTS

Box PCT

Alexandria, VA 22313

SIR:

Responsive to the notification dated November 30, 2005, and in accordance with the provisions of 35 U.S.C. 371, Applicants submit herewith a Rule 63 Declaration, a Supplemental Application Data Sheet, a General Power of Attorney, and a Statement Under 37 CFR 3.73 (b).

In light of the foregoing, this application is deemed to be in proper condition for examination and such favorable action is earnestly solicited.

Our payment in the amount of \$-0.00- is attached hereto. If any variance exists between the amount enclosed and the required Government fee, please charge or credit the difference to our Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

If these papers are not considered timely filed by the Patent and Trademark Office, then a petition is hereby made under 37 C.F.R. §1.136 and any additional fees required under 37 C.F.R. §1.136 for any necessary extension of time may be charged to Deposit Account No. 15-0030. A duplicate copy of this sheet is enclosed.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,  
MAIER & NEUSTADT, P.C.



Marvin J. Spivak  
Attorney of Record  
Registration No. 24,913  
Surinder Sachar  
Registration No. 34,423

Customer Number

**22850**

(703) 413-3000

**STATEMENT UNDER 37 CFR 3.73(b)**

Applicant/Patent Owner: Hiroshi SHIHO, et al.

Application No./Patent No.: 10/529,742 Filed/Issue Date: March 29, 2005

POLISHING PAD FOR SEMICONDUCTOR WAFER, POLISHING  
MULTILAYERED BODY FOR SEMICONDUCTOR WAFER HAVING SAME, AND

Entitled: METHOD FOR POLISHING SEMICONDUCTOR WAFER

JSR Corporation, a Corporation

(Name of Assignee)

(Type of Assignee, e.g., corporation, partnership, government agency, etc.)

States that it is:

1. ☒ the assignee of the entire right, title, and interest; or
2. ☐ an assignee of less than the entire right, title and interest.

The extent (by, percentage) of its ownership interest is \_\_\_\_\_ %

in the patent application/patent identified above by virtue of an assignment from the inventor(s) of the patent application/patent identified above. A copy of the assignment is attached. The assignment was previously recorded or is being recorded concurrently herewith.

The undersigned (whose title is supplied below) is authorized to act on behalf of the assignee.

Surinder Sachar

Registration No. 34,423

Signature

Jan 6 2006

Date

Marvin J. Spivak

Printed or Typed Name

703-413-3000

Telephone Number

24,913

Registration Number

## Assignment of Application

INSERT NAMES  
AND RESIDENCE  
ADDRESS OF  
THE INVENTORS:

WHEREAS, I (WE) Hiroshi SHIHO, Yukio HOSAKA, Kou HASEGAWA and Nobuo KAWAHASHI all of ; Tokyo,  
Japan

INSERT TITLE OF  
INVENTION:

have invented certain new and useful improvements in: POLISHING PAD FOR SEMICONDUCTOR WAFER AND  
LAMINATED BODY FOR POLISHING OF SEMICONDUCTOR WAFER EQUIPPED WITH THE SAME AS  
WELL AS METHOD FOR POLISHING OF SEMICONDUCTOR WAFER

(Application No. 10/529,742, filed March 29, 2005), and

INSERT NAME  
AND ADDRESS OF  
COMPANY OR  
OTHER ASSIGNEE

WHEREAS, JSR Corporation

(hereinafter referred to as "ASSIGNEE") having a place of business at: 6-10, Tsukiji 5-chome, Chuo-ku, Tokyo, Japan  
is desirous of acquiring the entire right, title and interest in and to said invention and in and to any Letters Patent that  
may be granted therefore in the United States and its territorial possessions and in any and all foreign countries;

NOW, THEREFORE, in consideration of the sum of FIVE DOLLARS (\$5.00), the receipt whereof is hereby  
acknowledged, and for other good and valuable consideration, I (WE), by these presents do sell, assign and transfer  
unto said ASSIGNEE, the full and exclusive right to the said invention in the United States and its territorial  
possessions and in all foreign countries and the entire right, title and interest in and to any and all Letters Patent which  
may be granted therefor in the United States and its territorial possessions and in any and all foreign countries and in  
and to any and all divisions, reissues, continuations, substitutions and renewals thereof.

I (WE) hereby authorize and request the Patent Office Officials in the United States and its territorial possessions  
and any and all foreign countries to issue any and all of said Letters Patent, when granted, to said ASSIGNEE as the  
assignee of my (our) entire right, title and interest in and to the same, for the sole use and behoof of said ASSIGNEE,  
its (his) successors and assigns, to the full end of the term for which said Letters Patent may be granted, as fully and  
entirely as the same would have been held by me (us) had this Assignment and sale not been made.

COPY

Further, I (WE) agree that I (WE) will communicate to said ASSIGNEE or its (his) representatives any facts known to me (us) respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal and reissue applications, execute all necessary assignment papers to cause any and all of said Letter Patent to be issued to said ASSIGNEE, make all rightful oaths, and, generally do everything possible to aid said ASSIGNEE, its (his) successors and assigns, to obtain and enforce proper protection for said invention in the United States and its territorial possessions and in any and all foreign countries.

The undersigned hereby grant(s) the firm of Oblon, Spivak, McClelland, Maier & Neustadt, P.C. of 1940 Duke Street, Alexandria, Virginia 22314 the power to insert on this assignment any further identification, including the application number and filing date, which may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

Date: April 8, 2005

Hiroshi Shiho  
(Signature of Inventor) Hiroshi SHIHO

Date: 2005-4-8

Yukio Hosaka  
(Signature of Inventor) Yukio HOSAKA

Date: April 8, 2005

Kou Hasegawa  
(Signature of Inventor) Kou HASEGAWA

Date: April 8, 2005

Nobuo Kawahashi  
(Signature of Inventor) Nobuo KAWAHASHI

Date: \_\_\_\_\_

\_\_\_\_\_  
(Signature of Inventor)

Date: \_\_\_\_\_

\_\_\_\_\_  
(Signature of Inventor)

**OBLON, SPIVAK, McCLELLAND, MAIER & NEUSTADT, P.C.**  
ATTORNEYS AT LAW  
1940 DUKE STREET  
ALEXANDRIA, VIRGINIA 22314

Res'd PCT/PTO 06 JAN 2006



## UNITED STATES PATENT AND TRADEMARK OFFICE

UNITED STATES DEPARTMENT OF COMMERCE  
 United States Patent and Trademark Office  
 Address: COMMISSIONER FOR PATENTS  
 P.O. Box 1450  
 Alexandria, Virginia 22313-1450  
 www.uspto.gov

U.S. APPLICATION NUMBER NO.	FIRST NAMED APPLICANT	ATTY. DOCKET NO.
10/529,742	Hiroshi Shiho	268844US2PCT

INTERNATIONAL APPLICATION NO.
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PCT/JP04/05963

I.A. FILING DATE	PRIORITY DATE
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04/23/2004

22850  
 OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C.  
 1940 DUKE STREET  
 ALEXANDRIA, VA 22314

CONFIRMATION NO. 8533

371 FORMALITIES LETTER



\*OC000000017495600\*

ET

Date Mailed: 11/30/2005

### NOTIFICATION OF MISSING REQUIREMENTS UNDER 35 U.S.C. 371 IN THE UNITED STATES DESIGNATED/ELECTED OFFICE (DO/EO/US)

The following items have been submitted by the applicant or the IB to the United States Patent and Trademark Office as a Designated / Elected Office (37 CFR 1.495).

- Copy of the International Application filed on 03/29/2005
- Copy of the International Search Report filed on 03/29/2005
- Preliminary Amendments filed on 05/03/2005
- Information Disclosure Statements filed on 03/29/2005
- Request for Immediate Examination filed on 03/29/2005
- U.S. Basic National Fees filed on 03/29/2005

RECEIVED: 12505  
 OBLON, SPIVAK, McCLELLAND  
 MAIER & NEUSTADT, P.C.

DOCKETING DEPT

Initials/Date Docketed: 12/12/05  
 Type of Resp(s): 09/ fees  
 Due Date(s): 1/30/06

12/23/06

The following items **MUST** be furnished within the period set forth below in order to complete the requirements for acceptance under 35 U.S.C. 371:

- Oath or declaration of the inventors, in compliance with 37 CFR 1.497(a) and (b), identifying the application by the International application number and international filing date.

## SUMMARY OF FEES DUE:

Total additional fees required for this application is \$-360 for a Large Entity:

(A previous payment of \$360 will be applied to the additional fees indicated above.)

**ALL OF THE ITEMS SET FORTH ABOVE MUST BE SUBMITTED WITHIN TWO (2) MONTHS FROM THE DATE OF THIS NOTICE OR BY 32 MONTHS FROM THE PRIORITY DATE FOR THE APPLICATION, WHICHEVER IS LATER. FAILURE TO PROPERLY RESPOND WILL RESULT IN ABANDONMENT.**

The time period set above may be extended by filing a petition and fee for extension of time under the provisions of 37 CFR 1.136(a).

Applicant is reminded that any communications to the United States Patent and Trademark Office must be mailed to the address given in the heading and include the U.S. application no. shown above (37 CFR 1.5)

A copy of this notice **MUST** be returned with the response.

FREDERICK SMITH

Telephone: (703) 308-9140 EXT 210

PART 1 - ATTORNEY/APPLICANT COPY

U.S. APPLICATION NUMBER NO.	INTERNATIONAL APPLICATION NO.	ATTY. DOCKET NO.
10/529,742	PCT/JP04/05963	268844US2PCT

FORM PCT/DO/EO/905 (371 Formalities Notice)